

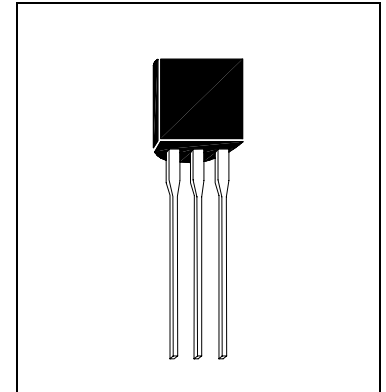


H2N6426

NPN EPITAXIAL PLANAR TRANSISTOR

Description

Darlington Transistor



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 BVCEO Collector to Emitter Voltage 40 V
 BVCBO Collector to Base Voltage 40 V
 BVEBO Emitter to Base Voltage 12 V
 IC Collector Current 500 mA

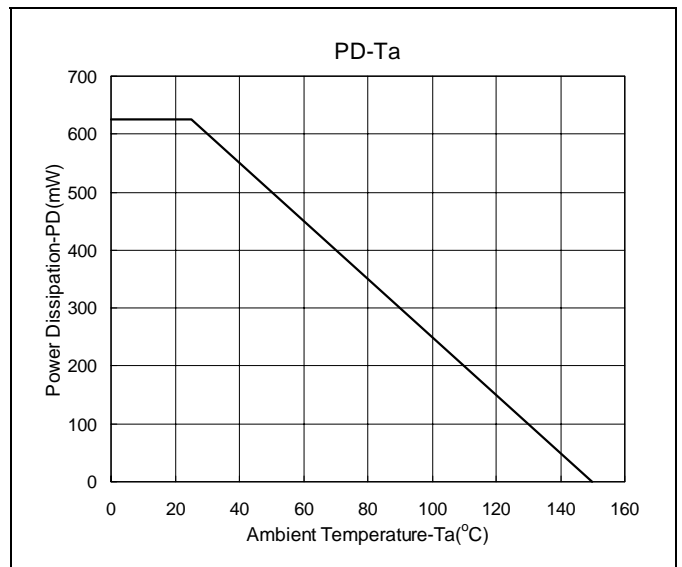
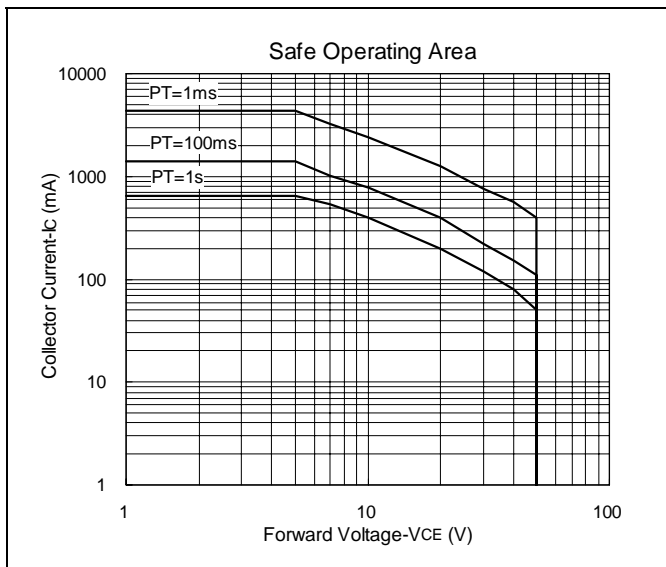
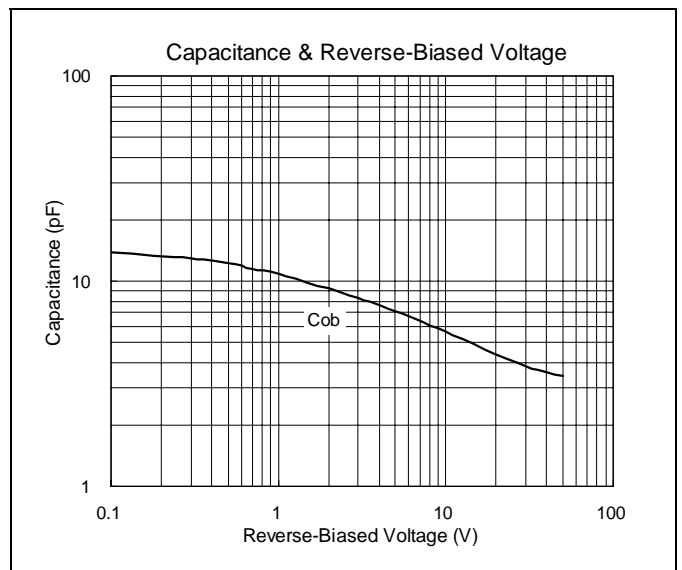
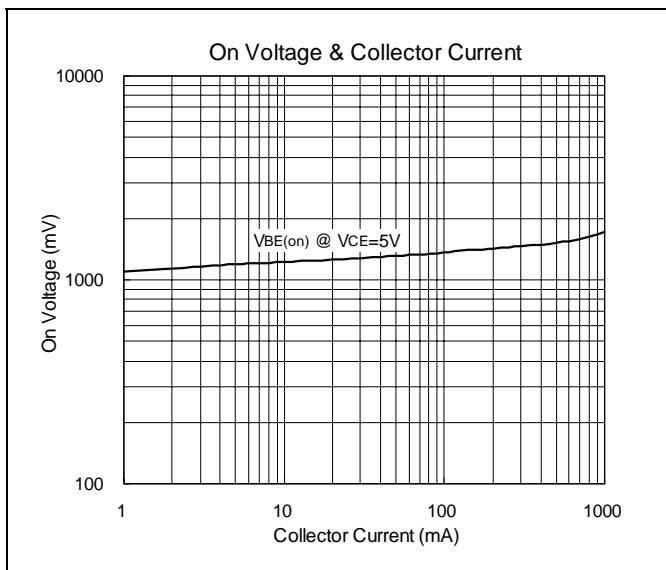
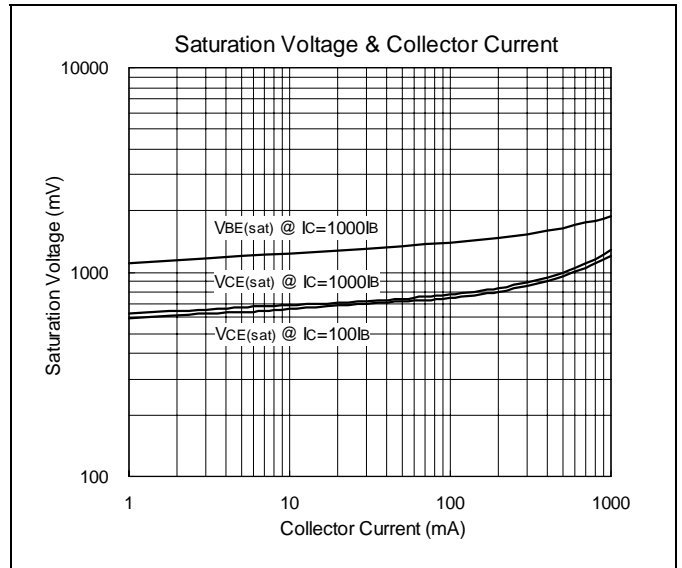
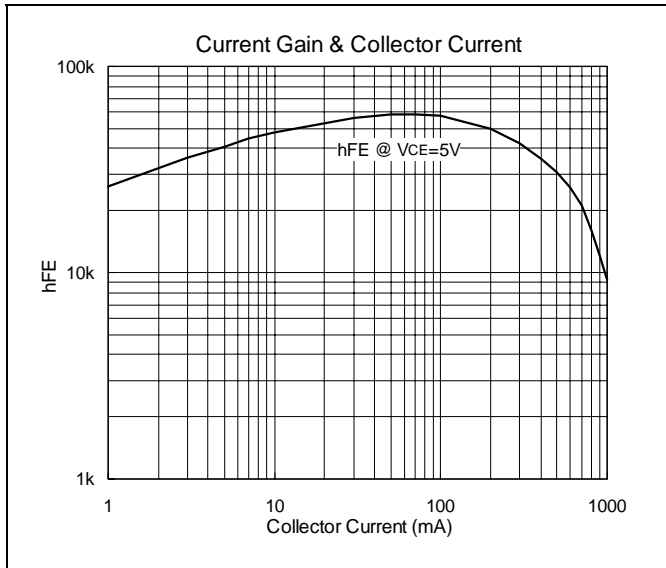
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	40	-	-	V	IC=10mA, IB=0
BVCBO	40	-	-	V	IC=100uA, IE=0
BVEBO	12	-	-	V	IE=10uA, IC=0
ICEO	-	-	1.0	uA	VEB=25V, IB=0
ICBO	-	-	50	nA	VCB=30V, IE=0
IEBO	-	-	50	nA	VEB=10V, IC=0
*VCE(sat)1	-	0.71	1.2	V	IC=50mA, IB=0.5mA
*VCE(sat)2	-	0.9	1.5	V	IC=500mA, IB=0.5mA
*VBE(sat)	-	1.52	2.0	V	IC=500mA, IB=0.5mA
VBE(on)	-	1.24	1.75	V	VCE=5V, IC=50mA
*hFE1	20	-	200	K	VCE=5V, IC=10mA
*hFE2	30	-	300	K	VCE=5V, IC=100mA
*hFE3	20	-	200	K	VCE=5V, IC=500mA
Cob	-	5.4	7.0	pF	VCB=10V, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

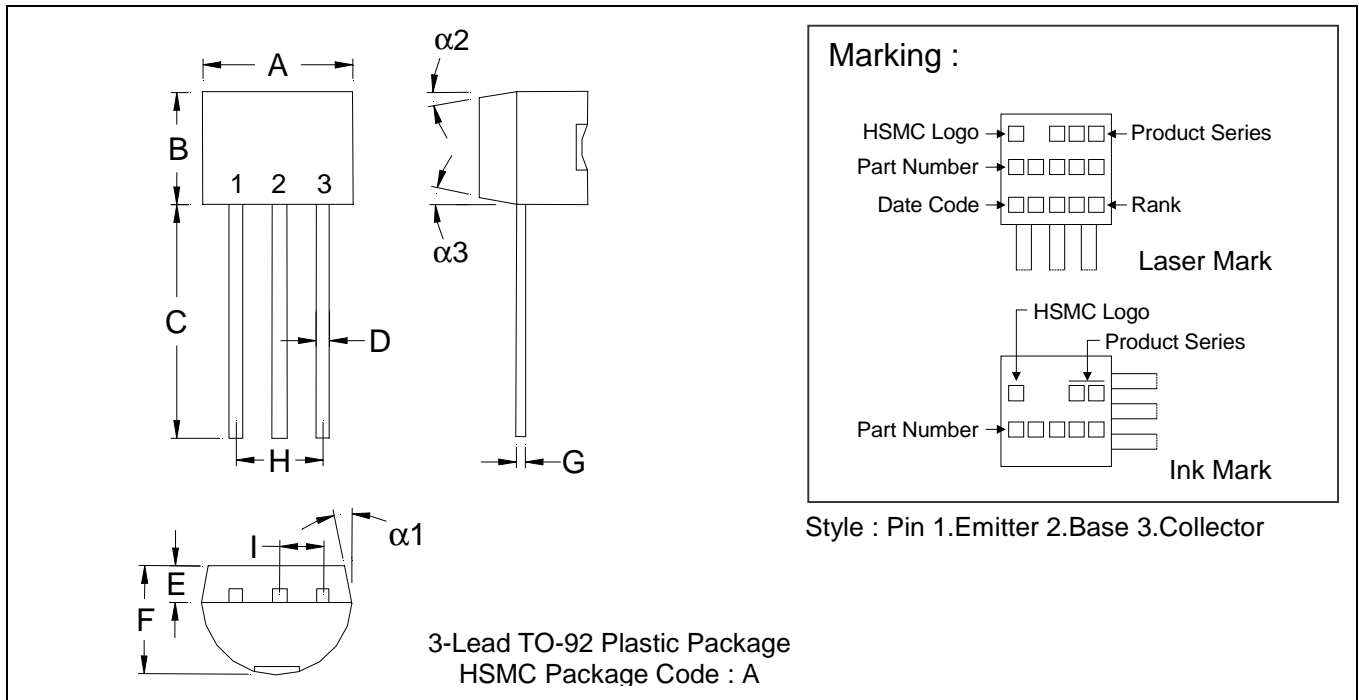


Characteristics Curve





TO-92 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5977061 Fax : 886-3-5979220